

### 2N6519

### **High Voltage Transistor**

- Collector-Emitter Voltage: V<sub>CEO</sub>= -300V
  Collector Dissipation: P<sub>C</sub> (max)=625mW



## **PNP Epitaxial Silicon Transistor**

1. Emitter 2. Base 3. Collector

### Absolute Maximum Ratings Ta=25°C unless otherwise noted

| Symbol           | Parameter                      | Value     | Units |
|------------------|--------------------------------|-----------|-------|
| V <sub>CBO</sub> | Collector-Base Voltage         | -300      | V     |
| V <sub>CEO</sub> | Collector-Emitter Voltage -300 |           | V     |
| V <sub>EBO</sub> | Emitter-Base Voltage           | -5        | V     |
| I <sub>C</sub>   | Collector Current              | -500      | mA    |
| I <sub>B</sub>   | Base Current                   | -250      | mA    |
| P <sub>C</sub>   | Collector Power Dissipation    | 625       | W     |
|                  | Derate above 25°C              | 5         | mW/°C |
| TJ               | Junction Temperature           | 150       | °C    |
| T <sub>STG</sub> | Storage Temperature            | -55 ~ 150 | °C    |

Refer to 2N6520 for graphs

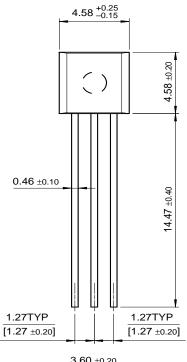
### **Electrical Characteristics** $T_a$ =25°C unless otherwise noted

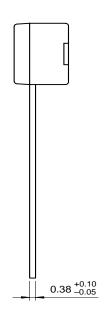
| Symbol                | Parameter                             | Test Condition   | Min.                       | Max.                          | Units       |
|-----------------------|---------------------------------------|--|----------------------------|-------------------------------|-------------|
| BV <sub>CBO</sub>     | Collector-Base Breakdown Voltage      | I <sub>C</sub> = -100μA, I <sub>E</sub> =0   | -300                       |                               | V           |
| BV <sub>CEO</sub>     | * Collector-Emitter Breakdown Voltage | I <sub>C</sub> = -1mA, I <sub>B</sub> =0   | -300                       |                               | V           |
| BV <sub>EBO</sub>     | Emitter-Base Breakdown Voltage        | I <sub>E</sub> = -10μA, I <sub>C</sub> =0  | -5                         |                               | V           |
| I <sub>CBO</sub>      | Collector Cut-off Current             | V <sub>CB</sub> = -200V, I <sub>E</sub> =0   |                            | -50                           | nA          |
| I <sub>EBO</sub>      | Emitter Cut-off Current               | V <sub>EB</sub> = -4V, I <sub>C</sub> =0   |                            | -50                           | nA          |
| h <sub>FE</sub>       | * DC Current Gain                     | V <sub>CE</sub> = -10V, I <sub>C</sub> = -1mA<br>V <sub>CE</sub> = -10V, I <sub>C</sub> = -10mA<br>V <sub>CE</sub> = -10V, I <sub>C</sub> = -30mA<br>V <sub>CE</sub> = -10V, I <sub>C</sub> = -50mA<br>V <sub>CE</sub> = -10V, I <sub>C</sub> = -100mA | 30<br>45<br>45<br>40<br>20 | 270<br>200                    |             |
| V <sub>CE</sub> (sat) | Collector-Emitter Saturation Voltage  | I <sub>C</sub> = -10mA, I <sub>B</sub> = -1mA<br>I <sub>C</sub> = -20mA, I <sub>B</sub> = -2mA<br>I <sub>C</sub> = -30mA, I <sub>B</sub> = -3mA<br>I <sub>C</sub> = -50mA, I <sub>B</sub> = -5mA   |                            | -0.30<br>-0.35<br>-0.50<br>-1 | V<br>V<br>V |
| V <sub>BE</sub> (sat) | Base-Emitter Saturation Voltage       | $I_{C}$ = -10mA, $I_{B}$ = -1mA<br>$I_{C}$ = -20mA, $I_{B}$ = -2mA<br>$I_{C}$ = -30mA, $I_{B}$ = -3mA  |                            | -0.75<br>-0.85<br>-0.90       | V<br>V<br>V |
| V <sub>BE</sub> (on)  | Base-Emitter On Voltage               | V <sub>CE</sub> = -10V, I <sub>C</sub> = -100mA  |                            | -2                            | V           |
| f <sub>T</sub>        | * Current Gain Bandwidth Product      | V <sub>CE</sub> = -20V, I <sub>C</sub> = -10mA, f=20MHz  | 40                         | 200                           | MHz         |
| C <sub>ob</sub>       | Output Capacitance                    | V <sub>CB</sub> = -20V, I <sub>E</sub> =0, f=1MHz  |                            | 6                             | pF          |
| C <sub>EB</sub>       | Emitter-Base Capacitance              | V <sub>EB</sub> = -0.5V, I <sub>C</sub> =0, f=1MHz   |                            | 100                           | pF          |
| t <sub>ON</sub>       | Turn On Time                          | $V_{BE}$ (off)= -2V, $V_{CC}$ = -100V $I_{C}$ = -50mA, $I_{B1}$ = -10mA  |                            | 200                           | ns          |
| t <sub>OFF</sub>      | Turn Off Time                         | $V_{CC}$ = -100V, $I_{C}$ = -50mA 3.5 $I_{B1}$ = $I_{B2}$ =10mA  |                            | ns                            |             |

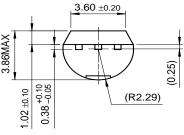
<sup>\*</sup> Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%

# **Package Dimensions**

TO-92







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| CoolFET™                   | FASTr™               | MicroFET™              | PowerTrench <sup>®</sup> | SuperSOT™-6            |
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